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N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

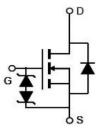
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- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS min@Tjmax}	550	V
R _{DS(ON)TYP} .	180	mΩ
I_D	13.5	Α
Qg	19	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

Device	Device Package	Marking
NCE50NF220	TO-220	NCE50NF220



Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _G s=0V)	VDS	500	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	V _G s	±30	V
Gate-Source Voltage (VDS=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	13.5	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	9.45	A
Pulsed drain current (Note 1)	I _{DM} (pluse)	40.5	A
Maximum Power Dissipation(Tc=25℃)	P _D	109	W
Derate above 25°C		0.72	W/°C
Single pulse avalanche current (Note 2)	I _{AS}	3	А
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15	V/ns
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_{J},T_{STG}	-55+175	°C



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	1.37	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
On/off states							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250uA	500			V	
Zero Gate Voltage Drain Current(Tc=25°ℂ)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			10	μA	
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =500V,V _{GS} =0V			100	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250uA	3		5	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6.5A		180	220	mΩ	
Dynamic Characteristics							
Gate Resistance	Rg	F=1MHZ, D-S short		15		Ω	
Input Capacitance	C _{lss}	., 50,4,4, 0,4		846		pF	
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V,		46		pF	
Reverse Transfer Capacitance	C _{rss}	F=1MHz		1.8		pF	
Total Gate Charge	Qg			19		nC	
Gate-Source Charge	Q _{gs}	V _{DS} =380V,I _D =6.5A,		7.3		nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		5.7		nC	
Gate plateau voltage	Vgp			6.6		V	
Switching times							
Turn-on Delay Time	t _{d(on)}			8		nS	
Turn-on Rise Time	t _r	V _{DD} =380V,I _D =6.5A,		10		nS	
Turn-Off Delay Time	t _{d(off)}	$R_G=4\Omega,V_{GS}=10V$		41		nS	
Turn-Off Fall Time	t _f			10		nS	
Source- Drain Diode Characteristics							
Source-drain current(Body Diode)	I _{SD}	T 0500			13.5	Α	
Pulsed-Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			40.5	Α	
Forward on voltage	V _{SD}	Tj=25°C,I _{SD} =13.5A,V _{GS} =0V		1.0	1.2	V	
Reverse Recovery Time	t _{rr}			150		nS	
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =6.5A,		0.34		uC	
Peak reverse recovery current	I _{rrm}	di/dt=100A/µs		4.5		Α	

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Output characteristics

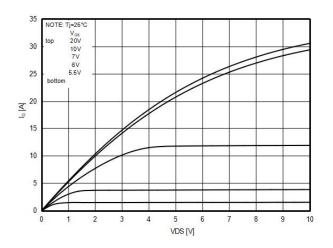


Figure 2. Transfer characteristics

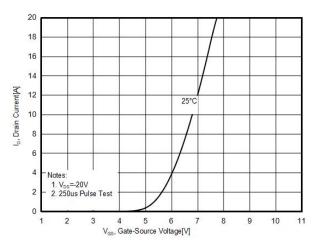


Figure 3. R_{DS(ON)} vs Junction Temperature

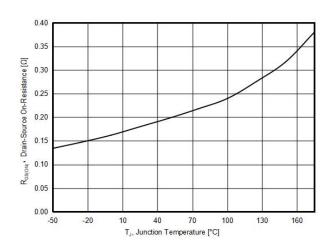


Figure 4. BV_{DSS} vs Junction Temperature

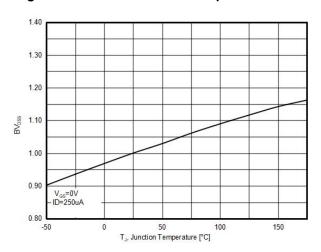


Figure 5. Maximum ID vs Junction Temperature

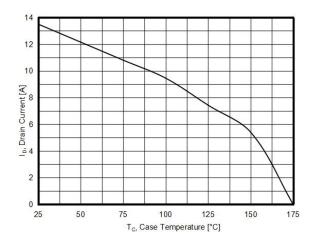
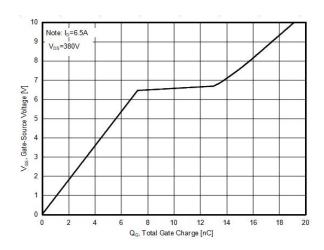


Figure 6. Gate charge waveforms



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Figure 7. Static drain-source on resistance

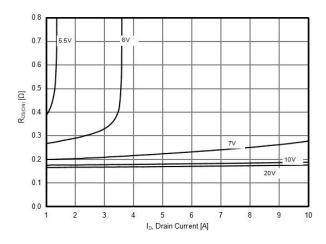


Figure9. Capacitance

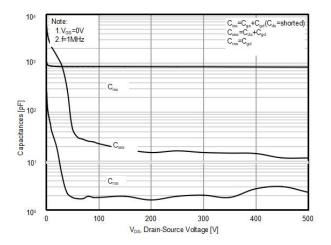


Figure8. Source-Drain Diode Forward Voltage

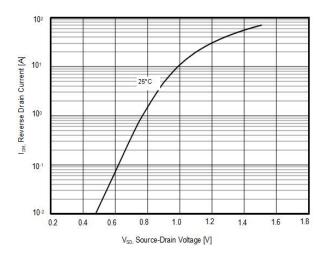
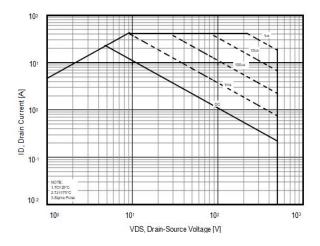


Figure 10. Safe operating area

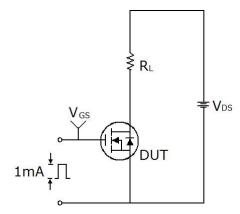


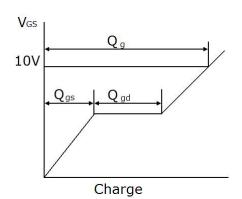
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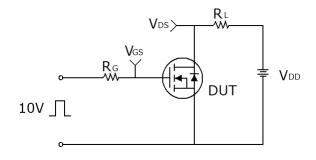
Test circuit

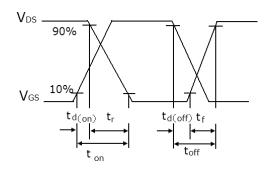
1) Gate charge test circuit & Waveform



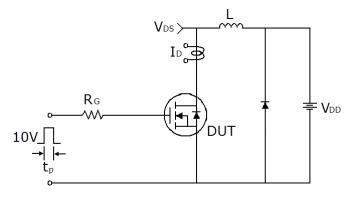


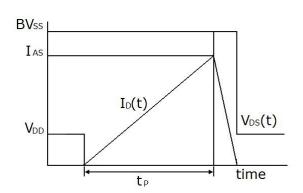
2) Switch Time Test Circuit:





3) Unclamped Inductive Switching Test Circuit & Waveforms

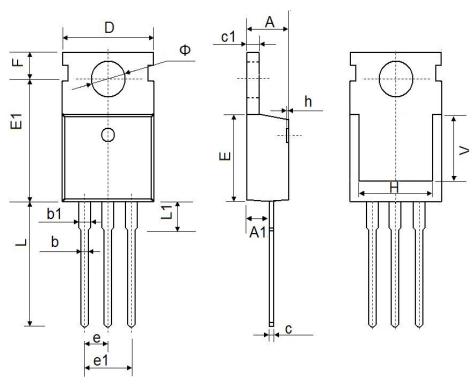




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TO-220-E Package Information

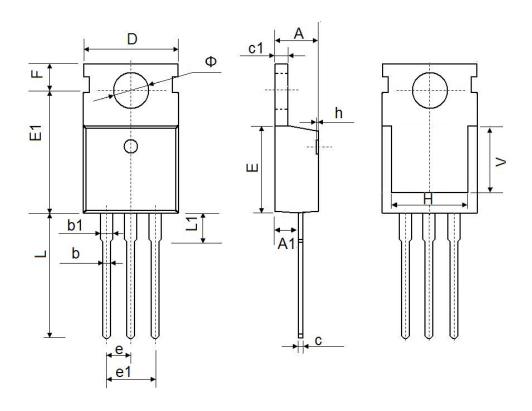


Symbol	Dimensions I	In Millimeters	Dimensions In Inches			
Cymbol	Min.	Max.	Min.	Max.		
А	4.20	4.60	0.165	0.181		
A1	2.25	2.55	0.089	0.100		
b	0.70	0.90	0.028	0.035		
b1	1.17	1.37	0.046	0.054		
С	0.33	0.65	0.013	0.026		
c1	1.20	1.40	0.047	0.055		
D	9.91	10.25	0.390	0.404		
E	8.95	9.75	0.352	0.384		
E1	12.80	12.90	0.504	0.508		
е	2.54	2.54BSC		0.100BSC		
e1	5.08	5.08BSC)BSC		
F	2.65	2.95	0.104	0.116		
Н	7.90	8.10	0.311	0.319		
L	12.90	13.40	0.508	0.528		
L1	2.85	3.25	0.112	0.128		
Ф	3.40	3.80	0.134	0.150		

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TO-220-S Package Information



Symbol	Dimensions	In Millimeters	Dimension	s In Inches
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
A1	2.25	2.55	0.089	0.1
b	0.71	0.91	0.028	0.036
b1	1.17	1.37	0.046	0.054
С	0.33	0.65	0.013	0.026
c1	1.2	1.4	0.047	0.055
D	9.91	10.25	0.39	0.404
E	8.95	9.75	0.352	0.384
E1	12.65	12.95	0.498	0.51
е	2.540	TYP.	0.100 TYP.	
e1	4.98	5.18	0.196	0.204
F	2.65	2.95	0.104	0.116
Н	7.9	8.1	0.311	0.319
h	0	0.3	0	0.012
L	12.9	13.4	0.508	0.528
L1	2.85	3.25	0.112	0.128
V	7.500	7.500 REF.		REF.
Ф	3.4	3.8	0.134	0.15



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